#### Light Emitting Diodes

## **Panasonic**

# LN220RPH

### Square Type

#### $\Box$ 1.75 mm $\times$ 7.0 mm

#### Absolute Maximum Ratings $T_a = 25^{\circ}C$

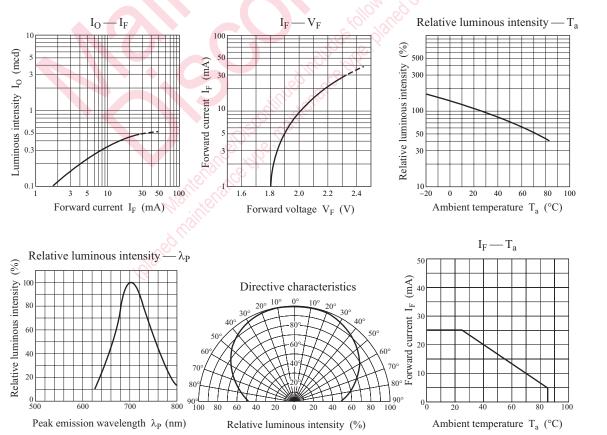
Parameter	Symbol	Rating	Unit	
Power dissipation	P <sub>D</sub>	70	mW	
Forward current	I <sub>F</sub>	25	mA	
Pulse forward current *	I <sub>FP</sub>	150	mA	
Reverse voltage	V <sub>R</sub>	4	V	
Operating ambient temperature	T <sub>opr</sub>	-25 to +85	°C	
Storage temperature	T <sub>stg</sub>	-30 to +100	°C	

Lighting Color

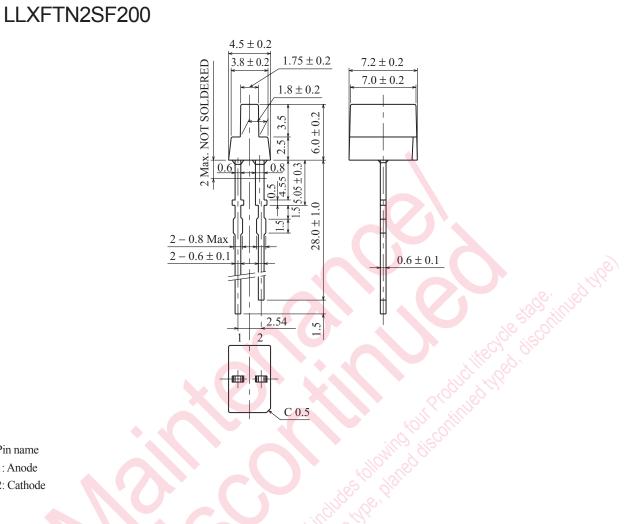
• Red

#### Electro-Optical Characteristics $T_a = 25^{\circ}C$

1 stg	50 10 + 100	6				
ith 1 msec.						
Electro-Optical Characteristics $T_a = 25^{\circ}C$					Un: 20	<sup>2</sup> 0
Symbol		Conditions	Min	Тур	Max	Unit
Io			0.15	0.4	5	mcd
I <sub>R</sub>	$V_R = 4 V$			1080	5	μΑ
V <sub>F</sub>	$I_F = 20 \text{ mA}$	X//	0,00,00	2.2	2.8	V
$\lambda_{\mathrm{P}}$	$I_F = 20 \text{ mA}$		JI AND	700		nm
Δλ	$I_F = 20 \text{ mA}$	enii		100		nm
	$Ith 1 msec.$ $= 25^{\circ}C$ Symbol $I_{O}$ $I_{R}$ $V_{F}$ $\lambda_{P}$	ith 1 msec.= $25^{\circ}C$ SymbolIoIoIRVR = $4 V$ VFIF = $20 \text{ mA}$ $\lambda_P$ IF = $20 \text{ mA}$	th 1 msec.= 25°CSymbolConditions $I_0$ $I_R$ $V_R = 4 V$ $V_F$ $I_F = 20 \text{ mA}$ $\lambda_P$ $I_F = 20 \text{ mA}$	Ith 1 msec.= 25°CSymbolConditionsMin $I_O$ 0.15 $I_R$ $V_R = 4 V$ $V_F$ $I_F = 20 \text{ mA}$ $\lambda_P$ $I_F = 20 \text{ mA}$	In the line of the lin	Ith 1 msec.         = 25°C         Symbol       Conditions       Min       Typ       Max $I_O$ 0.15       0.4       0.15       0.4 $I_R$ $V_R = 4 V$ 5       5 $V_F$ $I_F = 20 \text{ mA}$ 2.2       2.8 $\lambda_P$ $I_F = 20 \text{ mA}$ 700       00



Package (Unit: mm)



- Pin name
  - 1: Anode
  - 2: Cathode

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